Hot bump pull

Hot bump pull test method patented by Nordson DAGE that allows pads and interfaces to be pull tested using a heated copper pin.

The latest pad cratering standard, IPC-9708, defines hot bump pull as a method to evaluate the susceptibility of printed board assembly materials and designs to cohesive dielectric failure underneath surface mount technology attach pads. A method that can be used to rank order and compare different materials and parameters.

The Nordson DAGE 4000Plus HBP system is a totally industry unique solution, conforming to IPC-9708 as well as JEITA ET-7407A. It is fully integrated into a single load cartridge. Heating, cooling stages and pin clamping mechanism are integrated into the single load cartridge. The Paragon™ software provides a user friendly interface via temperature time profiles to setup a test. The cartridge design allow simple straight test pins to be used, allowing maximum force to be transferred as well as providing a low cost consumable for testing. The pin design provides successful and consistent testing. It is important to pull the pin vertically, directly by the apparatus without imposing any bending moments.

https://youtu.be/03ENLQ0w4u0
https://youtu.be/MkNKqOaOoSA
https://youtu.be/iS1fXxaHdq0